

**Search for Editor-In-Chief of the IEEE Transactions on Very Large Scale  
Integration (VLSI) Systems  
Call for Applications and Nominations**

The IEEE Transactions on Very Large Scale Integration (VLSI) Systems (TVLSI) is published as an archival monthly journal under the co-sponsorship of the IEEE Circuits and Systems Society, the IEEE Computer Society, and the IEEE Solid-State Circuits Society. We are currently seeking nominations and applications for the position of the Editor-in-Chief(EIC) of the IEEE TVLSI for the publication years 2019 and 2020. The design and realization of microelectronic systems based on nanometer VLSI technologies require multidisciplinary collaboration in the fields of systems architecture, logic and circuit design, integrated circuit fabrication, packaging, testing, systems applications, novel systems platforms (such as 3-D integration), and emerging technologies. Generation of specifications, design, and verification must be performed at all abstraction levels, including the system, register-transfer, logic, circuit, transistor, process, and materials levels. The IEEE TVLSI serves as a common forum to address these critical areas. The editorial board, consisting of international experts, invites original papers which emphasize and focus on the novel systems integration aspects of microelectronic systems, including interactions among systems design and partitioning, logic and memory design, digital and analog circuit design, physical design, layout synthesis, CAD tools, integrated circuit fabrication, testing and packaging, emerging technologies, and systems level design and analysis. Coverage of these Transactions will therefore focus on nanometer VLSI systems integration. For more information on the journal, refer to and <http://tvlsi.egr.duke.edu>. Applicants must have strong, relevant experience in roles such as author, reviewer, and associate editor for TVLSI and/or other related journals, and/or a technical program chair or similar roles in high-quality, peer-reviewed conferences. To attract high-quality papers to the journal, the EIC must also be a well-recognized leader in his/her areas of expertise. Key qualities of the EIC are an outstanding understanding of the needs of the research community at academic as well as industrial and government laboratories, awareness of changing emphases in research areas and development of emerging fields, plus the administrative skills to manage the editorial cycle in a timely fashion. The EIC must also be able to attract respected experts to his/her editorial board. The EIC must have good interpersonal skills to maintain good rapport with authors, editors, reviewers, and the IEEE staff. Applications or nominations must include an application/nomination letter, a complete curriculum vitae (CV), a personal statement summarizing their vision and plans for TVLSI, and also a letter from their employer indicating support for the EIC activity. The target start date for the new EIC is January 1, 2019.

Please send an email with the materials as a single zip file and with the subject line 'IEEE TVLSI EiC application' to: [henkel@kit.edu](mailto:henkel@kit.edu)  
(Make sure to receive a confirmation within two days of submission)

**Deadline for submission: April 30th 2018.**